CHEMTRONICS®
Technical Data Sheet

TDS # SWNoClean

Soder-Wick® No Clean Desoldering Braid

PRODUCT DESCRIPTION

Soder-Wick® No Clean is designed to provide fast and safe desoldering without leaving behind harmful flux residues. Soder-Wick® No Clean uses pure, oxygen free copper braid and a patented flux technology to make an efficient and effective desoldering braid. Soder-Wick® No Clean SD is available on ESD safe bobbins for protection against damage due to static electricity.

- Requires little or no post solder cleaning
- No corrosive residues
- Halide free
- ESD Safe bobbins meet specs:
  MIL-STD-1686C
  MIL-HDBK-263B
  Static decay provision of
  MIL-B-81705C
- Minimal risk of heat and static component damage

TYPICAL APPLICATIONS

Soder-Wick® No Clean safely removes solder from:

- Lugs and Posts
- Micro Circuits
- Surface Mount Device Pads
- Ball Grid Array Pads

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Surface Insulation Resistance

Bellcore TR-NWT-000078 : PASS
After 96 Hours (megohms) 2×10^4 Limit

Group A	Group B	Group C
4.8×10^6	3.8×10^6	4.1×10^6

ANSI/IPC J SF-818 : PASS
After 168 Hours (ohms) 1.8×10^8 Limit

1-2	2-3	3-4	4-5
2.3×10^{10}	2.6×10^{10}	2.8×10^{10}	2.8×10^{10}

Electromigration : PASS
Average Insulation Resistance (megohms)-One Decade Limit

	Initial	Final
Group E	3.93×10^3	1.24×10^4
Group F	3.87×10^3	2.84×10^4

At 10x magnification no evidence of electromigration or heavy corrosion.

Silver Chromate Test Paper	**PASS**
Copper Mirror Test	**PASS**
Shelflife	**2 years**
RoHS/WEEE Status	RoHS WEEE Compliant

SODER-WICK® NO CLEAN MEETS OR EXCEEDS:
MIL-F-14256F, Type R
DOD-STD-883E, Method 2022
Bellcore TR-NWT-000078
ANSI/IPC J SF-818

Part #	Size Inches	Color	Size Metric
1	.030”	White	.76mm
2	.060”	Yellow	1.52mm
3	.080”	Green	2.03mm
4	.110”	Blue	2.79mm
5	.145”	Brown	3.68mm
6	.210”	Red	5.33mm
BGA	-	Purple	-

USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

1) Choose a Soder-Wick® No Clean width equal to or slightly larger than the pad or connection.
2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
3) Set temperature of iron between 600-750°F.
4) Place wick on solder joint and place tip of hot iron on top of wick.
5) As solder becomes molten, the color of the wick will change from copper to silver.
6) Remove wick and iron from joint simultaneously once color change has stopped.
7) The component lead / pad is now clean and free from solder.
8) Clip and discard used portion of the wick.

TECHNICAL & APPLICATION ASSISTANCE

Chemtronics® provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.**

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AVAILABILITY

Part #	Size	Length	Part #	Size	Length
60-1-5	1	5	60-1-10	1	10
60-2-5	2	5	60-2-10	2	10
60-3-5	3	5	60-3-10	3	10
60-4-5	4	5	60-4-10	4	10
60-5-5	5	5	60-5-10	5	10
60-6-5	6	5			

VacuPak™ Packaging

The VacuPak™ Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

Part #	Size
SW16015	1
SW16025	2
SW16035	3
SW16045	4
SW16055	5
SW160BGA	BGA

NOTE:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. ITW Chemtronics® does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

MANUFACTURED BY:

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